PCB Stack Up

Layer	Type		Thickness (mil)			DK/DF
Top side solder mask				0.70	mils	4.1/0.022
L1	TOP	Signal	copper+plating	1.6	mils	
		TU-863P	1080 63%	2.72	mils	3.4/
L2		Signal	copper	1.4	mils	
		TU-863 substrate	core	4	mils	3.7/
L3		Signal	copper	0.7	mils	
		TU-863P TU-863P	1080 63% 1080 63%	5.58	mils	3.40/0.0000
L4		Signal	copper	1.4	mils	
		TU-863 substrate	core	4	mils	3.7/
L5		Signal	copper	1.4	mils	
		TU-863P TU-863P	1080 63% 1080 63%	5.58	mils	3.40/0.0000
L6		Signal	copper	0.7	mils	
		TU-863 substrate	core	4	mils	3.7/
L7		Signal	copper	1.4	mils	
		TU-863P	1080 63%	2.72	mils	3.4/0
L8	Bottom	Signal	copper+plating	1.6	mils	
Bottom side solder mask				0.70	mils	4.1/0.022
TOTAL				40.20	mils	
				1.02	mm	

Impedance

Single end				
LINE(mil)	Reference	ohm	TheoryValue	
4.00→4.50	L2	50	50.92	
4.00→4.50	L2/L4	50	49.71	
4.00→4.50	L5/L7	50	49.71	
4.00→4.50	L7	50	50.92	